



# 2017 IEEE



## Compound Semiconductor IC Symposium



INTEGRATED CIRCUITS and DEVICES in  
GaAs, InP, GaN, SiGe, and other compound semiconductor and CMOS technologies



October 22–25, 2017

Miami Marriott Biscayne Bay, USA



Sponsored by the IEEE Electron Devices Society  
Technically co-sponsored by the Solid State Circuits Society  
and the Microwave Theory & Techniques Society



## FIRST CALL FOR PAPERS

### 2017 CSIC Symposium

From its beginning in 1978 as the GaAs IC symposium, the IEEE Compound Semiconductor IC Symposium (CSICS) has evolved to become the preeminent international forum for developments in compound semiconductor integrated circuits and devices embracing GaAs, InP, GaN, SiGe, and CMOS technology. Coverage includes all aspects of the technology, from materials, device fabrication, IC design, testing, and system applications. CSICS provides the ideal forum to present the latest results in high-speed digital, analog, microwave, millimeter wave, THz, mixed-mode, and optoelectronic integrated circuits. First-time papers addressing the utilization and application of InP, GaAs, GaN, Silicon, Germanium, SiGe, and other compound semiconductors in military and commercial products are invited. Specific technical areas of interest include:

- High performance devices such as GaN power conversion devices, 700 GHz SiGe HBTs & InP HEMTs
- Novel devices such as tunnel FETs (TFETs), carbon nanotubes, MEMS, graphene & diamond transistors
- Integration of III-V devices on Si
- Optoelectronic and photonic devices such as optical modulators, lasers, photodetectors, and Silicon Photonics
- Device and circuit modeling concepts and implementation / EM and EDA tools
- Thermal management technologies, thermal simulation, and advanced packaging of high-power devices and ICs
- Device and IC manufacturing processes, testing methodologies, & reliability
- Analog, RF, mixed-signal, mm-wave, THz, power conversion and optoelectronic circuit blocks and ICs in III-V, CMOS, SiGe BiCMOS

### Symposium Highlights

High quality technical papers will be selected from worldwide submissions for oral presentation and publication in the Symposium Digest. Invited papers and panel sessions on topics of current importance to the Compound Semiconductor IC community will complete the program. Extended versions of selected papers from the Symposium will be published in a special issue of the *IEEE Journal of Solid State Circuits*.

### Primer Course

The Symposium will offer a primer course which is an introductory-level class intended for those wishing to obtain a broad and fundamental understanding of RFIC and High-Speed Analog-Mixed Signal technology. The Sunday course is designed to provide insight into the design of the principal RF building blocks, namely PAs, LNAs, Mixers and Oscillators, emphasizing the specific background needed for participants to understand and appreciate the papers presented in the Symposium Technical Program.

### Short Course

Two short courses will be held on Sunday, October 22, 2017. The courses are currently under development and will cover current topics in the industry. Organizer: Peter Zampardi, Qorvo, Ph: +1 805 480 5087, E-mail: [pete.zampardi@qorvo.com](mailto:pete.zampardi@qorvo.com)

### Deadline for Electronic Receipt of Abstracts is Close of Business, May 5, 2017

Authors must submit an Abstract (not more than 4 pages including figures and other supporting material) of results not previously published or not already accepted by another conference. Papers will be selected on the basis of the abstract.

The abstract must concisely and clearly state:

- The purpose of the work
- What specific new results have been obtained
- How it advances the state-of-the-art or the industry
- References to prior state-of-the-art
- Sub-committee preference:
  - Advanced Devices and Fabrication
  - Device Modeling and Simulation
  - Analog, RF, and Microwave ICs
  - mm-Wave and THz ICs
  - High-Speed digital, Mixed-Signal & Optoelectronic ICs

The abstract must include: the title, name(s) of the author(s), organization(s) represented, corresponding authors' postal and electronic addresses, and telephone and FAX numbers. Please indicate your preference for subcommittee review. The program committee will honor the authors' preference where possible, but reserves the right to place the paper in other review categories.

**Company and governmental clearances must be obtained prior to submission of the abstract.**

The accepted abstracts may be used for publicity purposes. Portions of these abstracts may be quoted in magazine articles publicizing the Symposium. **Please note on the abstract if this is not acceptable.**

Authors must submit the Abstract electronically using the [www.csics.org](http://www.csics.org) web page. Please note that the **only** accepted file format is **PDF**. Authors will be informed regarding the results of their submissions by June 16, 2017. Authors of accepted papers will be required to submit an **MS-Word version** of a 4-page camera-ready paper to IEEE by July 28, 2017 for publication in the Symposium Technical Digest.

Further questions on abstract submission may be addressed to the Symposium Technical Program Chair:

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All Symposium information, including abstract submission instructions and a link to our abstract submission address is available on the CSICS website at:

<http://www.csics.org>